

Copper

SLOTOCOUP BV 50

Copper SLOTOCOUP BV 50 is used for the production of HDI boards in order to fill blind microvias, pattern plating and to metallize through-holes in an one step process.

The layers deposited from Copper SLOTOCOUP BV 50 are very bright. The achievable levelling is extraordinary. Throwing power and metal distribution are excellent.

Copper SLOTOCOUP BV 50 was especially designed for operation in vertical plating lines equipped with copper anodes.

The metal distribution can be adapted to the printed circuit board's surface geometry by regulation of the current density and electrolyte composition.

Copper SLOTOCOUP BV 50 is operated with three liquid additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

